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ASE Inc. Management Team's Visit to SPIL's Chairman Mr. Bough Lin

Taipei, Taiwan, R.O.C., September 23, 2015 – Mr. Jason C.S. Chang, Chairman of Advanced Semiconductor Engineering, Inc. (TAIEX stock code: 2311, NYSE: ASX) ("**ASE**" or "**we**"), together with Chief Operating Officer Mr. Tien Wu and Chief Financial Officer Mr. Joseph Tung, met with Mr. Bough Lin, Chairman of Siliconware Precision Industries Co. Ltd ("**SPIL**"), to exchange ideas on the trends and developments in the global semiconductor industry as well as ASE's tender offer for SPIL common shares and American depository shares (the "**Tender Offer**"):

1. ASE is regretful for not being able to discuss the Tender Offer with SPIL beforehand due to certain legal restrictions, which may have prohibited SPIL's management team from fully understanding the purpose of our Tender Offer. We sincerely hope that Chairman Lin and SPIL's management could understand our difficult position.
2. With SPIL's employees and shareholders' rights and interests in mind, we are looking forward to building a foundation to explore avenues of cooperation with SPIL in the face of raising challenges from intensifying global competition and the trends of consolidation within the global semiconductor industry. On this note, we would like to reiterate that we will not intervene in SPIL's operations. We sincerely hope that both companies' management can build on their hard work over the past thirty years, and work towards enhancing the competitiveness of the Taiwan semiconductor testing industry as well as the overall economic development of Taiwan for a better future.
3. ASE is not able to comment on the potential strategic benefits of the strategic alliance and vertical integration between SPIL and Hon Hai Precision Industry Co., Ltd. ("**Hon Hai**"), as we do not have knowledge on the specific details of the strategic alliance arrangement. However, we believe that SPIL's proposed issuance of new shares to facilitate the share exchange with Hon Hai (the "**Hon Hai Deal**") would be dilutive for SPIL's existing shareholders. As we will not be able to exercise our voting right at SPIL's extraordinary shareholders' meeting scheduled on October 15, 2015, we would like to express to Chairman Lin our strong objection against the Hon Hai Deal. We trust that Chairman Lin and SPIL's management team will take into account shareholders' rights and interests when the management seriously re-evaluates whether the Hon Hai Deal was truly necessary and appropriate, and whether the actions to implement the Hon Hai Deal were in compliance with the relevant laws and regulations.

Safe Harbor Notice:

This press release contains "forward-looking statements" within the meaning of Section 27A of the United States Securities Act of 1933, as amended, and Section 21E of the United States Securities Exchange Act of 1934, as amended, including statements regarding our future results of operations and business prospects. Although these forward-looking statements, which may include statements regarding our future results of operations, financial condition or business prospects, are based on our own information and information from other sources we believe to

be reliable, you should not place undue reliance on these forward-looking statements, which apply only as of the date of this press release. The words “anticipate,” “believe,” “estimate,” “expect,” “intend,” “plan” and similar expressions, as they relate to us, are intended to identify these forward-looking statements in this press release. Our actual results of operations, financial condition or business prospects may differ materially from those expressed or implied in these forward-looking statements for a variety of reasons, including risks associated with cyclical and market conditions in the semiconductor or electronic industry; changes in our regulatory environment, including our ability to comply with new or stricter environmental regulations and to resolve environmental liabilities; demand for the outsourced semiconductor packaging, testing and electronic manufacturing services we offer and for such outsourced services generally; the highly competitive semiconductor or manufacturing industry we are involved in; our ability to introduce new technologies in order to remain competitive; international business activities; our business strategy; our future expansion plans and capital expenditures; the strained relationship between the Republic of China and the People’s Republic of China; general economic and political conditions; the recent global economic crisis; possible disruptions in commercial activities caused by natural or human-induced disasters; fluctuations in foreign currency exchange rates; and other factors. For a discussion of these risks and other factors, please see the documents we file from time to time with the Securities and Exchange Commission, including our 2014 Annual Report on Form 20-F filed on March 18, 2015.